

SID

Factory: Rot am See

Article:

ML6

Provided:

Customer:

Date:

24.04.2026

**WÜRTH
ELEKTRONIK**
MORE THAN
YOU EXPECT

Processtechnology: B: Pinlamination C: Pinlamination

Material Text	Mat. Nr.	µm		Stackup	Process overview	
A-RS Kupferfolie-009my 330x490mm	50201012	9	VS	1		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	62		2		
A-RS Kupferfolie-009my 330x490mm	50201012	35	L2	3		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	124		4		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		5		
C-RS-FR4-ML-0.203mm-035+035-TG150-HF-...	50203019	35	L3	6		A00 B00 C00
		203				
		35	L4			
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	124		7		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		8		
A-RS Kupferfolie-009my 330x490mm	50201012	35	L5	9		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	62		10		
A-RS Kupferfolie-009my 330x490mm	50201012	9	RS	11		

Thickness after Pressing

B00: 591 µm

Tol+: 59 µm

Tol-: 59 µm

Dmax: 650 µm

Dmin: 532 µm

C00: 690 µm

Tol+: 100 µm

Tol-: 100 µm

Dmax: 790 µm

Dmin: 590 µm

Thickness over all

0 µm

Tol+: 0 µm

Tol-: 0 µm

Dmax: 0 µm

Dmin: 0 µm

Demand for customer

Thickness (D): 800 µm

Tol+: 100 µm

Tol-: 100 µm

Dmax: 900 µm

Dmin: 700 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal: 733 µm

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